

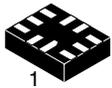
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

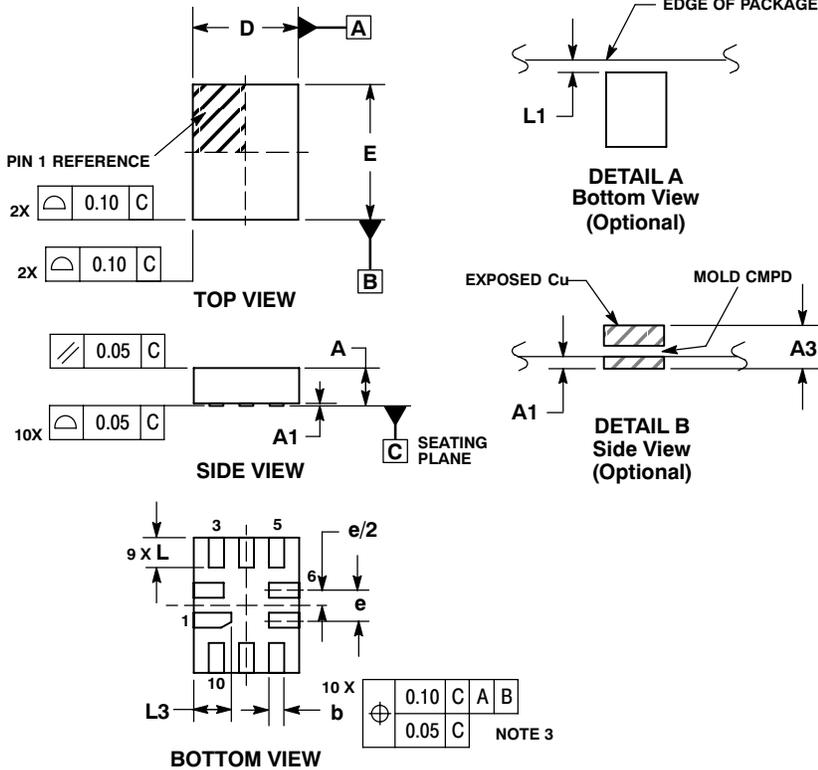


UQFN10 1.4x1.8, 0.4P CASE 488AT-01 ISSUE A

DATE 01 AUG 2007



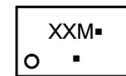
SCALE 5:1



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETERS
 - DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 - COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.40	BSC
E	1.80	BSC
e	0.40	BSC
L	0.30	0.50
L1	0.00	0.15
L3	0.40	0.60

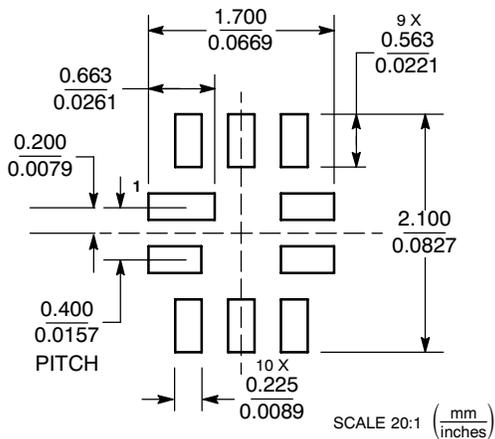
GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
 M = Date Code
 ■ = Pb-Free Package
 (Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

MOUNTING FOOTPRINT



DOCUMENT NUMBER:	98AON22493D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	10 PIN UQFN, 1.4 X 1.8, 0.4P	PAGE 1 OF 2

